



# PMEG2005BELD

20 V, 0.5 A low VF Schottky barrier rectifier

2 November 2022

Product data sheet

## 1. General description

Planar Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a leadless ultra small SOD882D (DFN1006D-2) Surface-Mounted Device (SMD) plastic package with visible and solderable side pads.

## 2. Features and benefits

- Average forward current:  $I_{F(AV)} \leq 0.5$  A
- Reverse voltage:  $V_R \leq 20$  V
- Low forward voltage  $V_F \leq 390$  mV
- Ultra small and leadless SMD plastic package
- Solderable side pads
- Package height typ. 0.37 mm

## 3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Reverse polarity protection
- Low power consumption applications
- Ultra high-speed switching
- LED backlight for mobile application

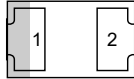

## 4. Quick reference data

Table 1. Quick reference data

| Symbol      | Parameter               | Conditions   | Min | Typ | Max | Unit    |
|-------------|-------------------------|--|-----|-----|-----|---------|
| $I_{F(AV)}$ | average forward current | $\delta = 0.5$ ; $f = 20$ kHz; square wave; $T_{sp} \leq 140$ °C                   | -   | -   | 0.5 | A       |
| $V_R$       | reverse voltage         | $T_j = 25$ °C  | -   | -   | 20  | V       |
| $V_F$       | forward voltage         | $I_F = 500$ mA; $t_p \leq 300$ $\mu$ s; $\delta \leq 0.02$ ; pulsed; $T_j = 25$ °C | -   | 353 | 390 | mV      |
| $I_R$       | reverse current         | $V_R = 20$ V; $T_j = 25$ °C  | -   | 87  | 200 | $\mu$ A |

## 5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description            | Simplified outline   | Graphic symbol  |
|-----|--------|------------------------|--|---|
| 1   | K      | cathode <sup>[1]</sup> |  <p>Transparent top view</p> <p><b>DFN1006D-2 (SOD882D)</b></p> |  <p>aaa-003679</p> |
| 2   | A      | anode                  |  |   |

[1] The marking bar indicates the cathode.

## 6. Ordering information

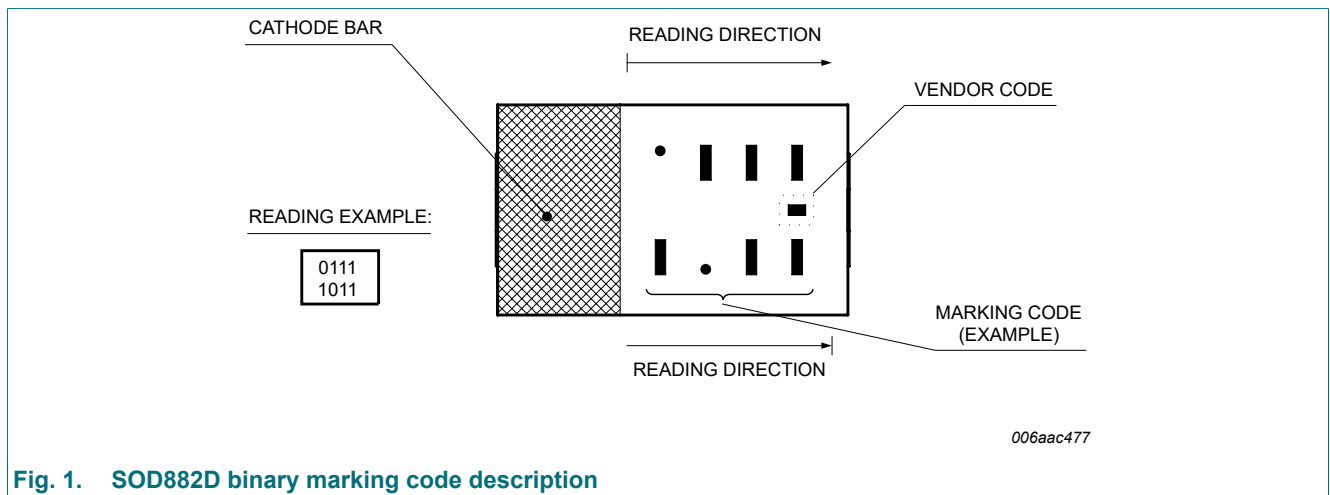
Table 3. Ordering information

| Type number                  | Package    |   |                         |
|------------------------------|------------|---|-------------------------|
|                              | Name       | Description   | Version                 |
| <a href="#">PMEG2005BELD</a> | DFN1006D-2 | leadless ultra small plastic package with side-wettable flanks (SWF); 2 terminals; 0.65 mm pitch; 1 mm x 0.6 mm x 0.4 mm body | <a href="#">SOD882D</a> |

## 7. Marking

Table 4. Marking codes

| Type number  | Marking code |
|--------------|--------------|
| PMEG2005BELD | 0010<br>1000 |



## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol      | Parameter                           | Conditions   |         | Min | Max  | Unit |
|-------------|-------------------------------------|--|---------|-----|------|------|
| $V_R$       | reverse voltage                     | $T_j = 25\text{ °C}$   |         | -   | 20   | V    |
| $I_F$       | forward current                     | $T_{sp} \leq 140\text{ °C}$  |         | -   | 0.5  | A    |
| $I_{F(AV)}$ | average forward current             | $\delta = 0.5$ ; $f = 20\text{ kHz}$ ; square wave; $T_{sp} \leq 140\text{ °C}$  |         | -   | 0.5  | A    |
|             |                                     | $\delta = 0.5$ ; $f = 20\text{ kHz}$ ; square wave; $T_{amb} \leq 115\text{ °C}$ | [1]     | -   | 0.5  | A    |
| $I_{FRM}$   | repetitive peak forward current     | $t_p \leq 1\text{ ms}$ ; $\delta \leq 0.25$                                      |         | -   | 3    | A    |
| $I_{FSM}$   | non-repetitive peak forward current | $t_p = 8\text{ ms}$ ; square wave; $T_{j(\text{init})} = 25\text{ °C}$           |         | -   | 6    | A    |
| $P_{tot}$   | total power dissipation             | $T_{amb} \leq 25\text{ °C}$  | [2] [3] | -   | 370  | mW   |
|             |                                     |  | [1] [3] | -   | 735  | mW   |
|             |                                     |  | [4] [3] | -   | 1135 | mW   |
| $T_j$       | junction temperature                |  |         | -   | 150  | °C   |
| $T_{amb}$   | ambient temperature                 |  |         | -55 | 150  | °C   |
| $T_{stg}$   | storage temperature                 |  |         | -65 | 150  | °C   |

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for cathode  $1\text{ cm}^2$ .

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Reflow soldering is the only recommended soldering method.

[4] Device mounted on a ceramic PCB,  $\text{Al}_2\text{O}_3$ , standard footprint.

## 9. Thermal characteristics

**Table 6. Thermal characteristics**

| Symbol         | Parameter  | Conditions  |                | Min | Typ | Max | Unit |
|----------------|--|-------------|----------------|-----|-----|-----|------|
| $R_{th(j-a)}$  | thermal resistance from junction to ambient      | in free air | [1] [2]<br>[3] | -   | -   | 340 | K/W  |
|                |  |             | [1] [4]<br>[3] | -   | -   | 170 | K/W  |
|                |  |             | [1] [5]<br>[3] | -   | -   | 110 | K/W  |
| $R_{th(j-sp)}$ | thermal resistance from junction to solder point |             | [6]            | -   | -   | 25  | K/W  |

[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses  $P_R$  are a significant part of the total power losses.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Reflow soldering is the only recommended soldering method.

[4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode  $1\text{ cm}^2$ .

[5] Device mounted on a ceramic PCB,  $\text{Al}_2\text{O}_3$ , standard footprint.

[6] Soldering point of cathode tab.

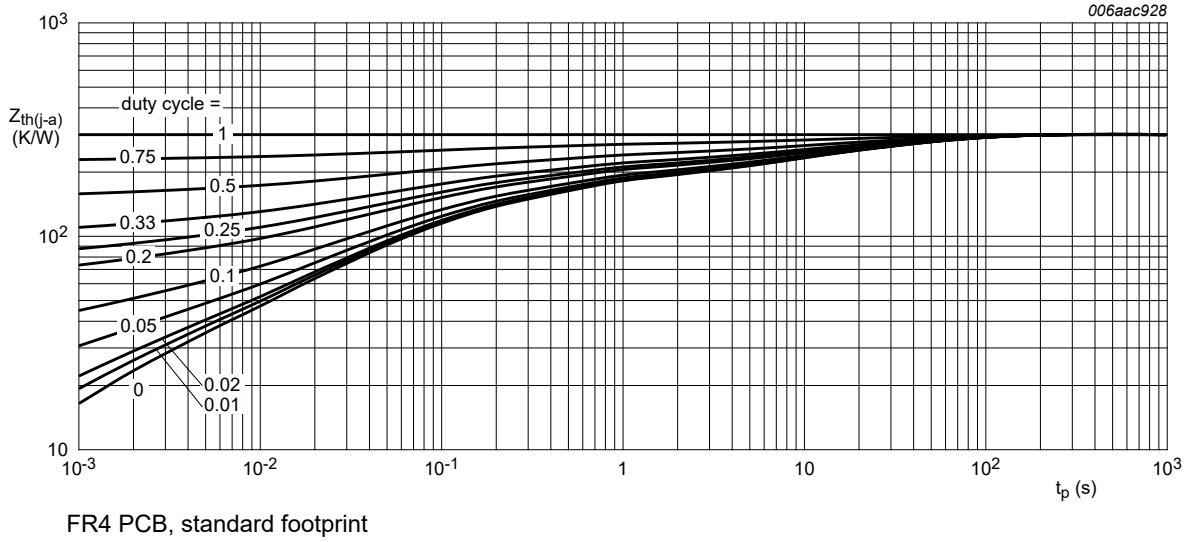


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

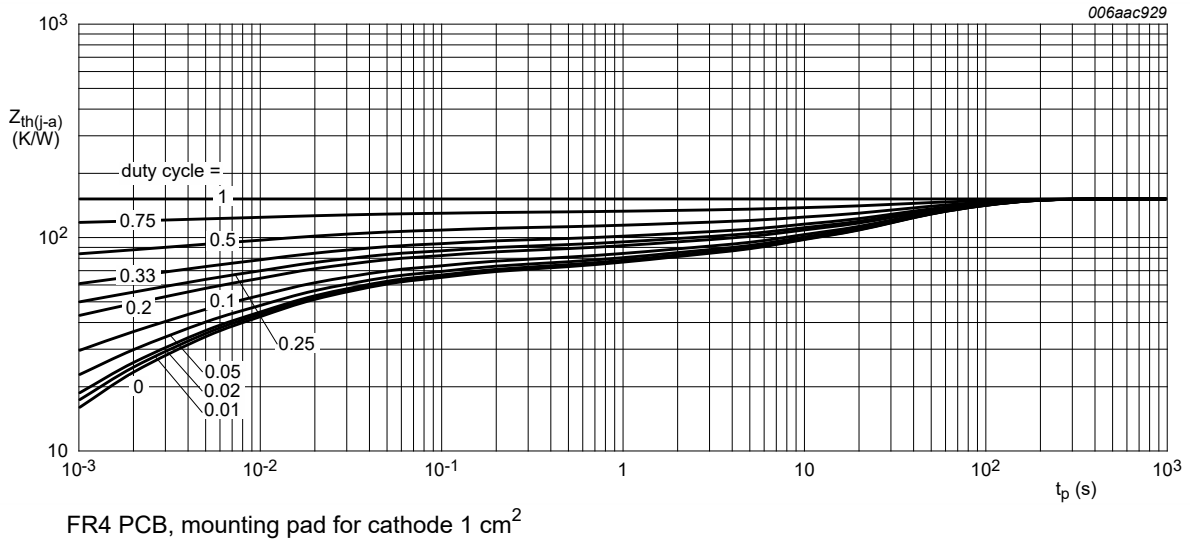


Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

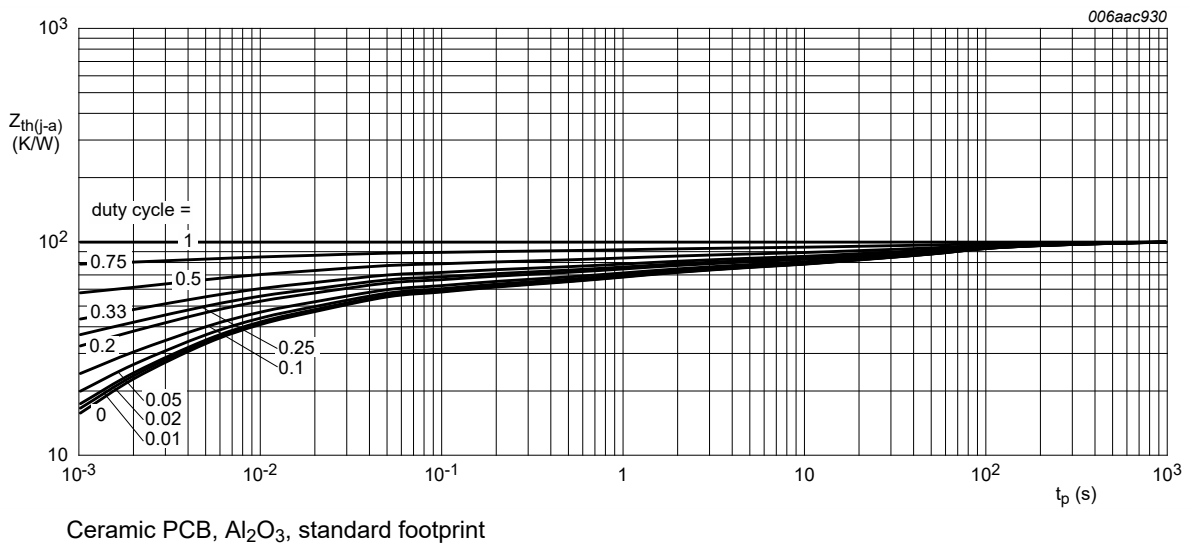
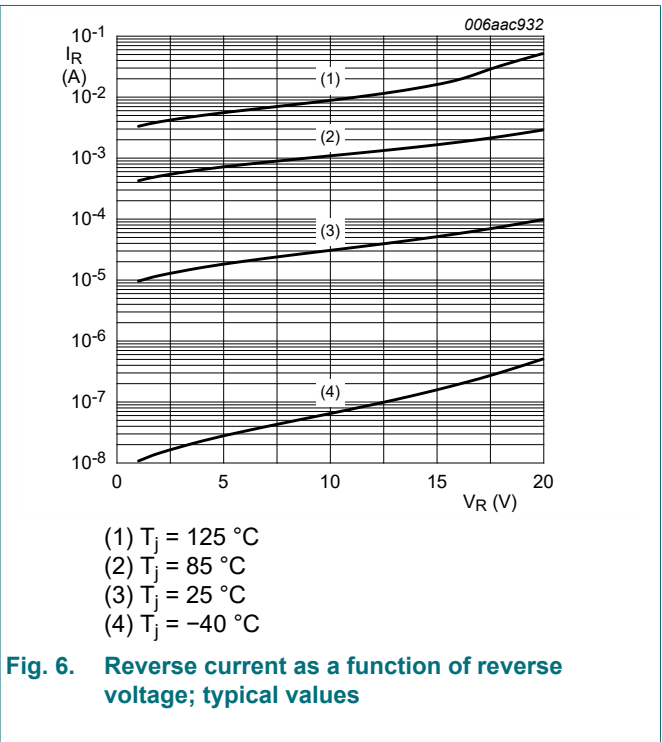
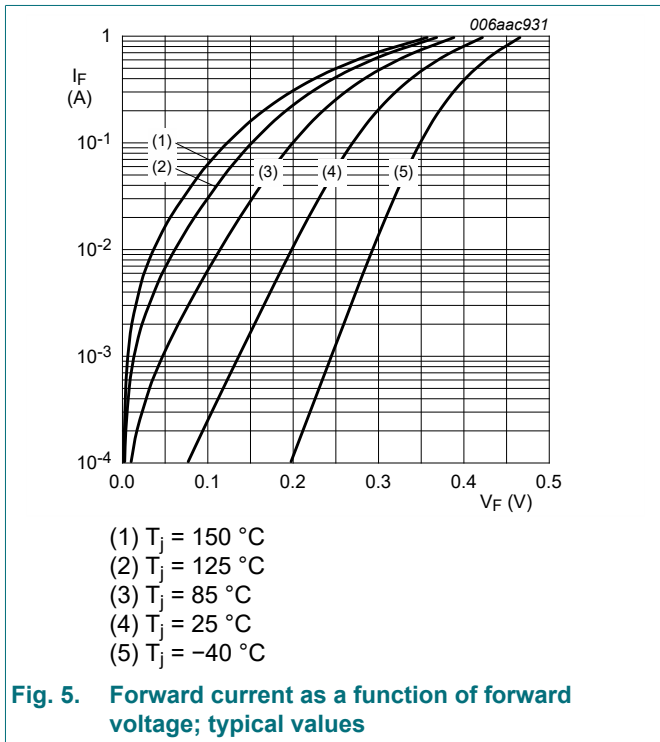


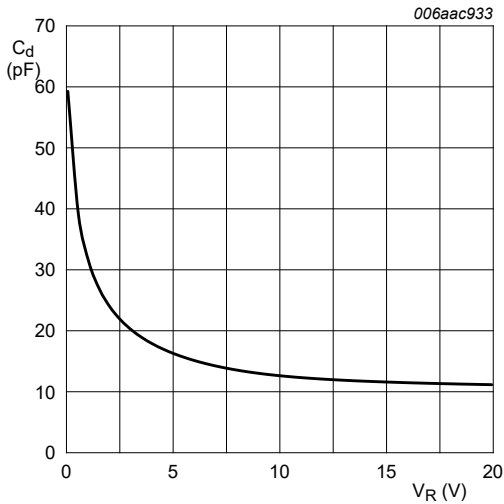
Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

### 10. Characteristics

Table 7. Characteristics

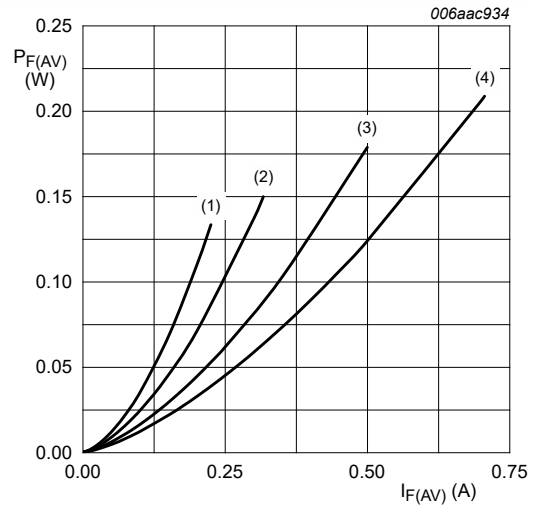
| Symbol           | Parameter                     | Conditions   | Min | Typ | Max | Unit |
|------------------|-------------------------------|--|-----|-----|-----|------|
| V <sub>F</sub>   | forward voltage               | I <sub>F</sub> = 0.1 mA; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; pulsed; T <sub>j</sub> = 25 °C           | -   | 79  | 105 | mV   |
|                  |                               | I <sub>F</sub> = 1 mA; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; pulsed; T <sub>j</sub> = 25 °C             | -   | 137 | 170 | mV   |
|                  |                               | I <sub>F</sub> = 10 mA; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; pulsed; T <sub>j</sub> = 25 °C            | -   | 197 | 235 | mV   |
|                  |                               | I <sub>F</sub> = 100 mA; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; pulsed; T <sub>j</sub> = 25 °C           | -   | 266 | 310 | mV   |
|                  |                               | I <sub>F</sub> = 500 mA; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; pulsed; T <sub>j</sub> = 25 °C           | -   | 353 | 390 | mV   |
| I <sub>R</sub>   | reverse current               | V <sub>R</sub> = 10 V; T <sub>j</sub> = 25 °C  | -   | 28  | 50  | μA   |
|                  |                               | V <sub>R</sub> = 20 V; T <sub>j</sub> = 25 °C  | -   | 87  | 200 | μA   |
| C <sub>d</sub>   | diode capacitance             | V <sub>R</sub> = 1 V; f = 1 MHz; T <sub>j</sub> = 25 °C  | -   | 31  | 40  | pF   |
| t <sub>rr</sub>  | reverse recovery time         | I <sub>F</sub> = 0.5 A; I <sub>R</sub> = 0.5 A; I <sub>R(meas)</sub> = 0.1 A; T <sub>j</sub> = 25 °C | -   | 1.6 | -   | ns   |
| V <sub>FRM</sub> | peak forward recovery voltage | I <sub>F</sub> = 0.5 A; dI <sub>F</sub> /dt = 20 A/μs; T <sub>j</sub> = 25 °C                        | -   | 565 | -   | mV   |





$f = 1 \text{ MHz}; T_{amb} = 25 \text{ }^\circ\text{C}$

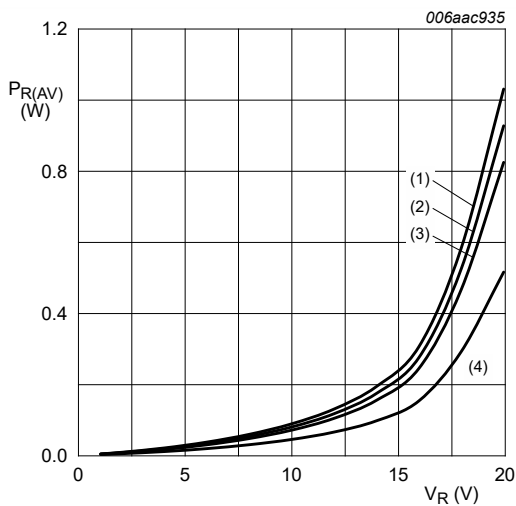
**Fig. 7. Diode capacitance as a function of reverse voltage; typical values**



$T_j = 150 \text{ }^\circ\text{C}$

- (1)  $\delta = 0.1$
- (2)  $\delta = 0.2$
- (3)  $\delta = 0.5$
- (4)  $\delta = 1$

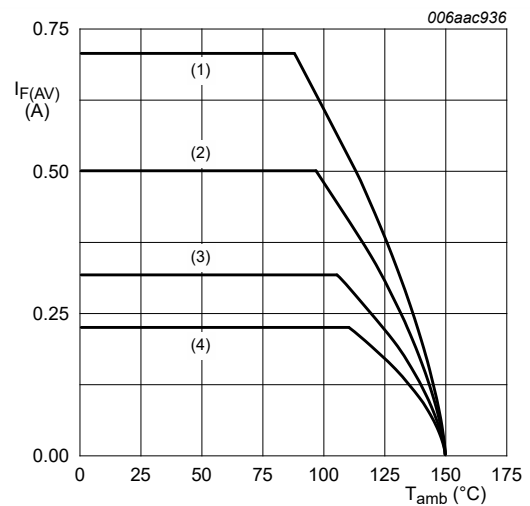
**Fig. 8. Average forward power dissipation as a function of average forward current; typical values**



$T_j = 125 \text{ }^\circ\text{C}$

- (1)  $\delta = 1$  (DC)
- (2)  $\delta = 0.9; f = 20 \text{ kHz}$
- (3)  $\delta = 0.8; f = 20 \text{ kHz}$
- (4)  $\delta = 0.5; f = 20 \text{ kHz}$

**Fig. 9. Average reverse power dissipation as a function of reverse voltage; typical values**

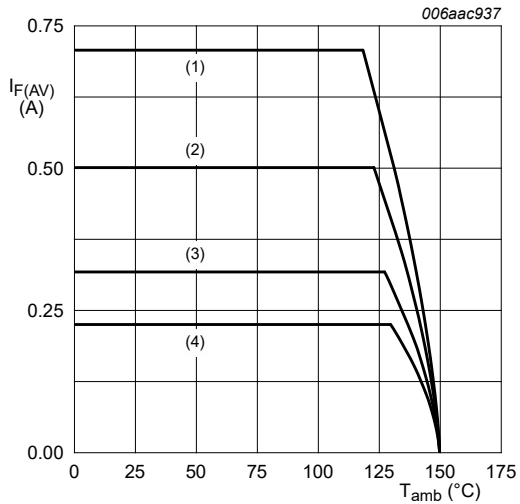


FR4 PCB, standard footprint

$T_j = 150 \text{ }^\circ\text{C}$

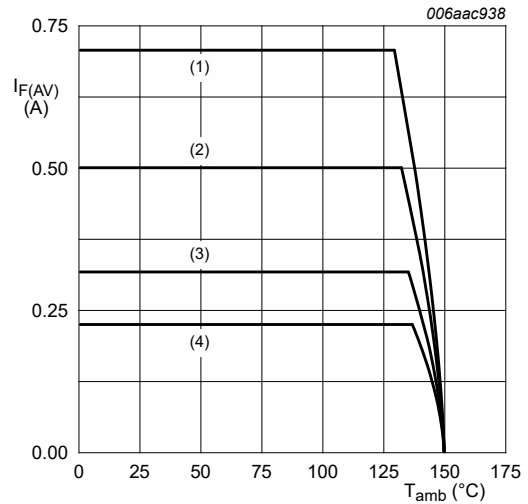
- (1)  $\delta = 1$
- (2)  $\delta = 0.5$
- (3)  $\delta = 0.2$
- (4)  $\delta = 0.1$

**Fig. 10. Average forward current as a function of ambient temperature; typical values**



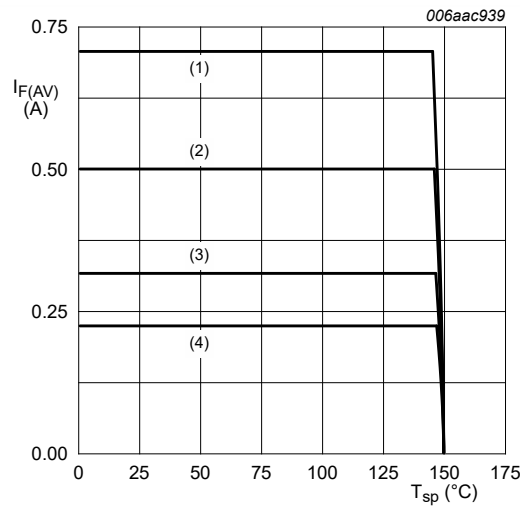
FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>  
 $T_j = 150\text{ °C}$   
 (1)  $\delta = 1$   
 (2)  $\delta = 0.5$   
 (3)  $\delta = 0.2$   
 (4)  $\delta = 0.1$

Fig. 11. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint  
 $T_j = 150\text{ °C}$   
 (1)  $\delta = 1$   
 (2)  $\delta = 0.5$   
 (3)  $\delta = 0.2$   
 (4)  $\delta = 0.1$

Fig. 12. Average forward current as a function of ambient temperature; typical values



$T_j = 150\text{ °C}$   
 (1)  $\delta = 1$   
 (2)  $\delta = 0.5$   
 (3)  $\delta = 0.2$   
 (4)  $\delta = 0.1$

Fig. 13. Average forward current as a function of solder point temperature; typical values

### 11. Test information



Fig. 14. Reverse recovery definition

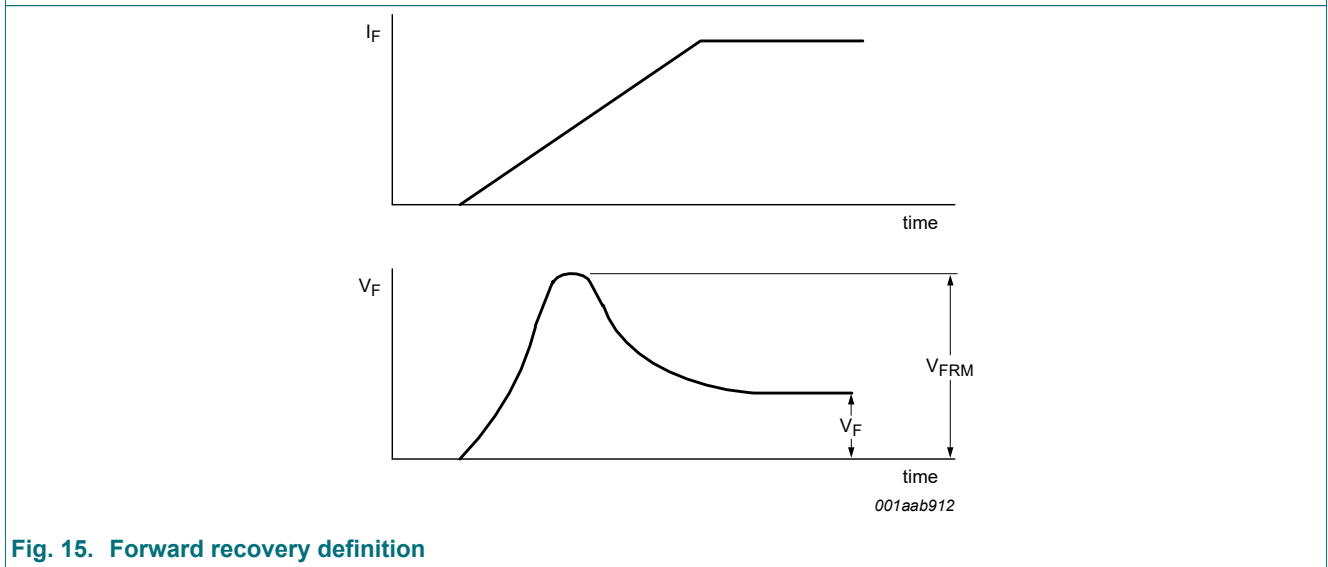


Fig. 15. Forward recovery definition

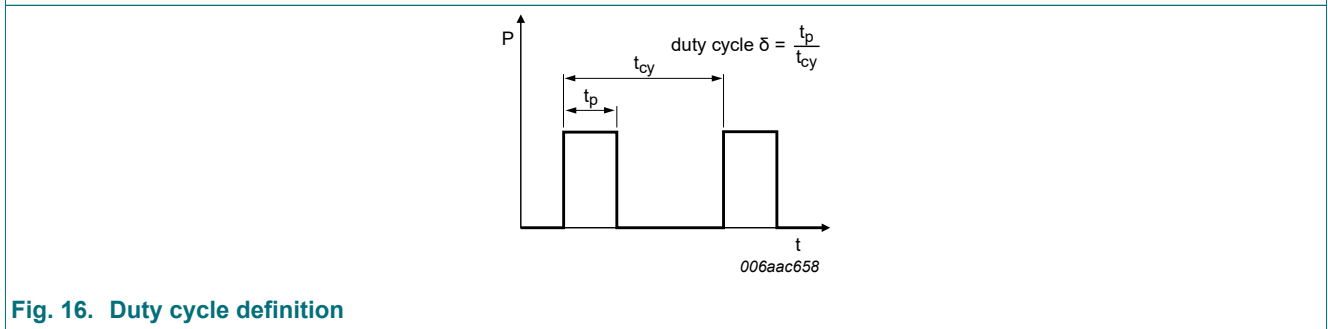
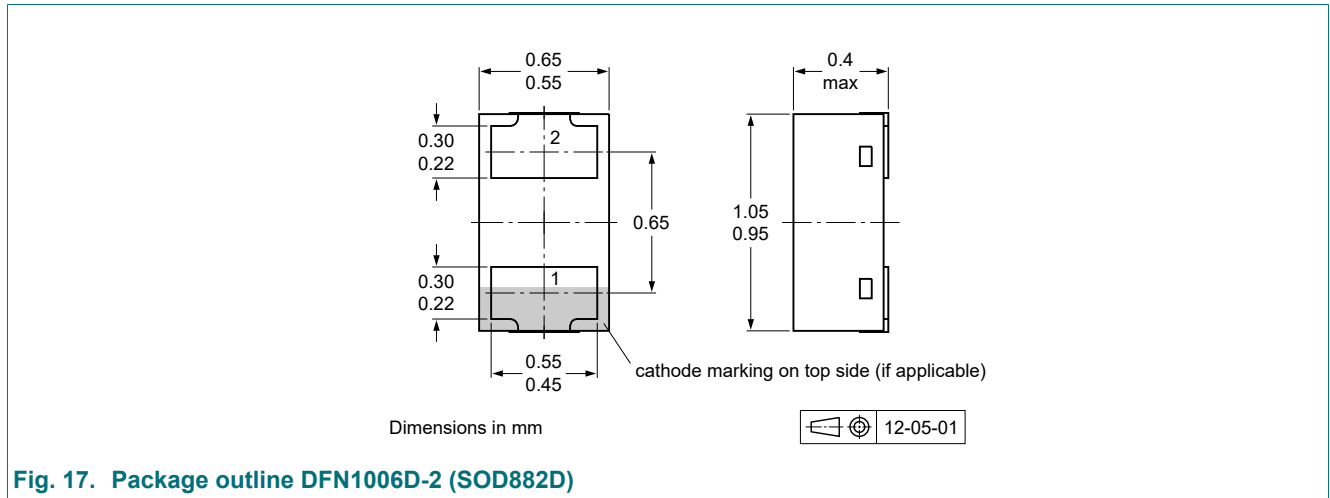


Fig. 16. Duty cycle definition

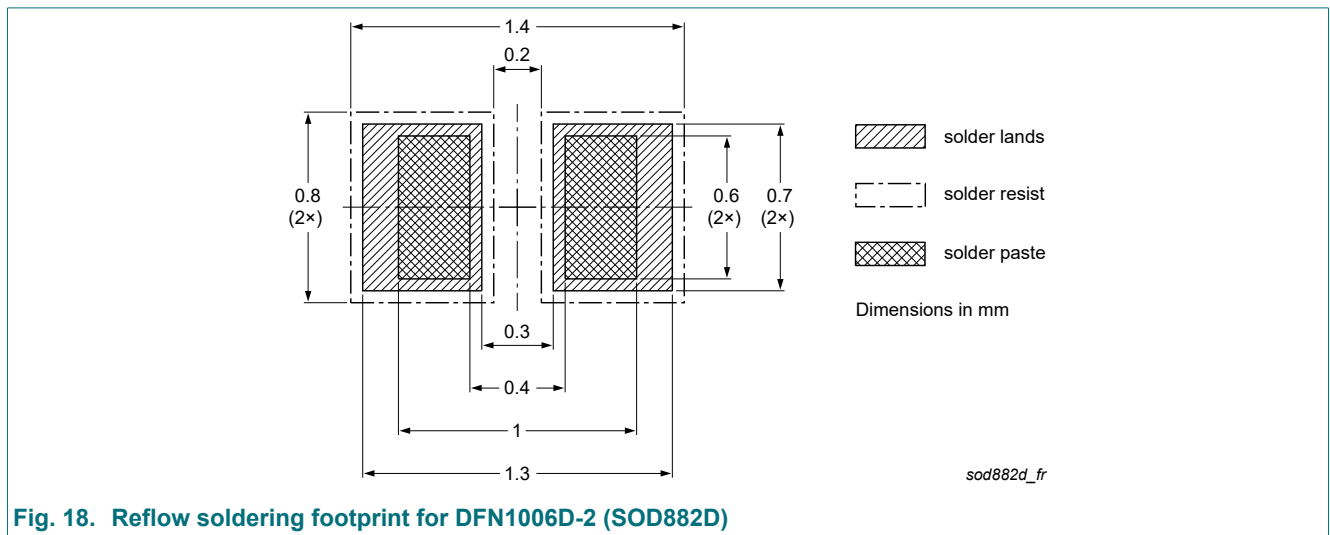
The current ratings for the typical waveforms are calculated according to the equations:  
 $I_{F(AV)} = I_M \times \delta$  with  $I_M$  defined as peak current,  $I_{RMS} = I_{F(AV)}$  at DC, and  $I_{RMS} = I_M \times \sqrt{\delta}$  with  $I_{RMS}$  defined as RMS current.



## 12. Package outline



## 13. Soldering



## 14. Revision history

Table 8. Revision history

| Document ID      | Release date   | Document status        | Change notice | Supersedes       |
|------------------|--|------------------------|---------------|------------------|
| PMEG2005BELD v.5 | 20221102   | Product data sheet     | -             | PMEG2005BELD v.4 |
| Modifications:   | <ul style="list-style-type: none"> <li>Product(s) changed to non-automotive qualification. Please refer to nexperia.com for automotive (-Q) product alternative(s).</li> </ul> |                        |               |                  |
| PMEG2005BELD v.4 | 20150804   | Product data sheet     | -             | PMEG2005BELD v.3 |
| PMEG2005BELD v.3 | 20120704   | Product data sheet     | -             | PMEG2005BELD v.2 |
| PMEG2005BELD v.2 | 20120312   | Product data sheet     | -             | PMEG2005BELD v.1 |
| PMEG2005BELD v.1 | 20120111   | Preliminary data sheet | -             | -                |

## 15. Legal information

### Data sheet status

| Document status [1][2]         | Product status [3] | Definition  |
|--------------------------------|--------------------|---|
| Objective [short] data sheet   | Development        | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification      | This document contains data from the preliminary specification.                       |
| Product [short] data sheet     | Production         | This document contains the product specification.                                     |

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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